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DEVICE SPECIFICATION FOR

Control-PWB unit

MODEL No.

LP0DZC0002

These parts are complied with the RoHS directive.

*If you have any problems to this specification, please let us know before placing an order.

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RECORDS OF REVISION

Model No.: LP0DZC0002

| SPEC No. | DATE | REVISED No. | PAGE | SUMMARY | MARKS |
|------------|-----------|-------------|------|---------|-------|
| LD-2025203 | 21-Feb-25 | - | - | - | |

1. Application

This specification applies to the following Control-PWB unit (C-PWB) that can only be used exclusively for the following TFT-EPD Open-Cell. Each electrical characteristic is defined in combination with the following TFT-EPD Open-Cell.

| Model No. | SDTC Product No. | SDTC Part Code | Mating Open-Cell Model No. | SDTC Product No. | Remarks |
|------------|------------------|----------------|----------------------------|------------------|---------|
| LP0DZC0002 | A1LP0DZC0002 | RUNTK7033TPZZ | LP285A6NW01 | A1LP285A6NW01 | |

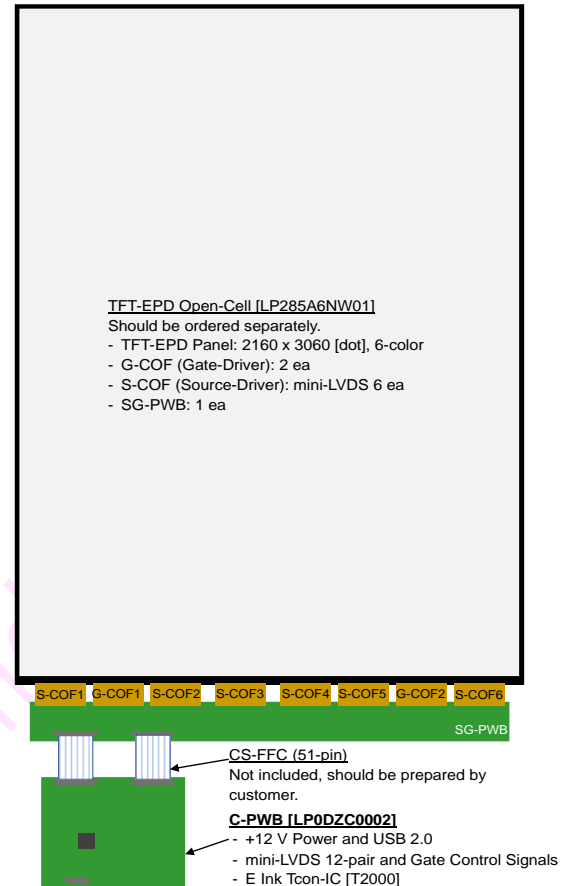
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In case of using the device for applications such as control and safety equipment for transportation, aircraft, trains, automobiles, etc., rescue and security equipment and various safety related equipment which require higher reliability and safety, take into consideration that appropriate measures such as fail-safe functions and redundant system design should be taken.

Do not use the device for equipment that requires an extreme level of reliability, such as aerospace applications, telecommunication equipment (trunk lines), nuclear power control equipment, and medical or other equipment for life support.

SC and SDTC assumes no responsibility for any damage resulting from the use of the device that does not comply with the instructions and the precautions specified in this specification.

Contact and consult with a SDTC sales representative for any questions about this product.



2. Overview

This C-PWB has the following features.

- Only for the TFT-EPD Open-Cell by SDTC, **LP285A6NW01**.
- 6 colors (White/Red/Green/Blue/Yellow/Black) displayable on the TFT-EPD Open-Cell with +12 V Power Supply and USB 2.0 input.

3. Mechanical Specifications

3.1. Main Specifications

| Items | Specifications | Units |
|--------------------------|---|-------|
| Outline | 120 x 100 | mm |
| Thickness | Total: 5.2 (Max., 51-pin CNT) PWB: 1.0±0.1 | mm |
| Weight | 0.05 | kg |
| PWB Material | FR-4.1 | - |
| PWB Layer Structure | 4-layer | - |
| Surface treatment | ENIG | - |
| PWB UL Type | ML1 | - |
| PWB UL Frame-proof Grade | 94V-0 | - |
| PWB UL No. | E253117 | - |

4.2. Output Specifications

CN4: To CN1 of LP285A6NW01

- Using connector: 187059-51221 [P-TWO] or compatible
- Mating connector: 187104-51001-3 [P-TWO] or compatible

| Pin No. | Pin Names | Functions | Remarks |
|---------|-----------|------------------------------|---------------|
| 1 | MODE | Gate driver output control | ²⁾ |
| 2 | XON | No Connection | |
| 3 | STBYB | mini-LVDS enable | ¹⁾ |
| 4 | NC | No Connection | |
| 5 | NC | No Connection | |
| 6 | NC | No Connection | |
| 7 | NC | No Connection | |
| 8 | VGL | Gate Driver Negative Power | |
| 9 | VGL | Gate Driver Negative Power | |
| 10 | NC | No Connection | |
| 11 | VN3 | Source Driver Negative Power | |
| 12 | VN3 | Source Driver Negative Power | |
| 13 | VN3 | Source Driver Negative Power | |
| 14 | NC | No Connection | |
| 15 | VN2 | Source Driver Negative Power | |
| 16 | VN2 | Source Driver Negative Power | |
| 17 | VN2 | Source Driver Negative Power | |
| 18 | NC | No Connection | |
| 19 | VN1 | Source Driver Negative Power | |
| 20 | VN1 | Source Driver Negative Power | |
| 21 | VN1 | Source Driver Negative Power | |
| 22 | NC | No Connection | |
| 23 | GND | Ground | |
| 24 | GND | Ground | |
| 25 | NC | No Connection | |
| 26 | VDD | Logic Power | |
| 27 | VDD | Logic Power | |
| 28 | NC | No Connection | |
| 29 | VP1 | Source Driver Positive Power | |
| 30 | VP1 | Source Driver Positive Power | |
| 31 | VP1 | Source Driver Positive Power | |
| 32 | NC | No Connection | |
| 33 | VP2 | Source Driver Positive Power | |
| 34 | VP2 | Source Driver Positive Power | |
| 35 | VP2 | Source Driver Positive Power | |
| 36 | NC | No Connection | |
| 37 | VP3 | Source Driver Positive Power | |
| 38 | VP3 | Source Driver Positive Power | |
| 39 | VP3 | Source Driver Positive Power | |
| 40 | NC | No Connection | |
| 41 | VGH | Gate Driver Positive Power | |
| 42 | VGH | Gate Driver Positive Power | |
| 43 | NC | No Connection | |
| 44 | NC | No Connection | |
| 45 | NC | No Connection | |
| 46 | VCOM | Common Voltage | ⁶⁾ |
| 47 | VCOM | Common Voltage | ⁶⁾ |
| 48 | NC | No Connection | |
| 49 | VCOM | Common Voltage | ⁶⁾ |
| 50 | VCOM | Common Voltage | ⁶⁾ |
| 51 | VCOM | Common Voltage | ⁶⁾ |

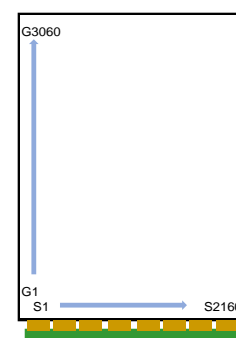
CN5: To CN2 of LP285A6 NW01

- Using connector: 187059-51221 [P-TWO] or compatible
- Mating connector: 187104-51001-3 [P-TWO] or compatible

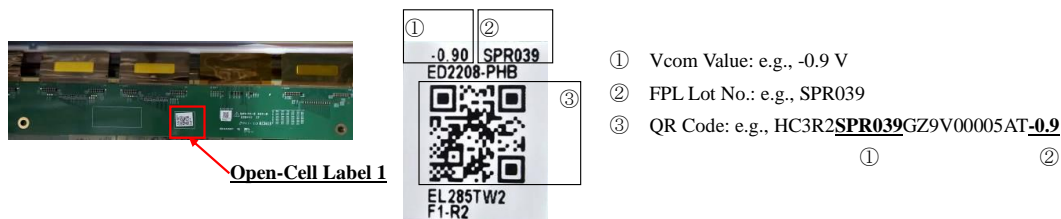
| Pin No. | Pin Names | Functions | Remarks |
|---------|-----------|--------------------------------------|---------------|
| 1 | GND | Ground | |
| 2 | LV0P | mini-LVDS data signal | ⁶⁾ |
| 3 | LV0N | mini-LVDS data signal | ⁶⁾ |
| 4 | GND | Ground | |
| 5 | LV1P | mini-LVDS data signal | ⁶⁾ |
| 6 | LV1N | mini-LVDS data signal | ⁶⁾ |
| 7 | GND | Ground | |
| 8 | LV2P | mini-LVDS data signal | ⁶⁾ |
| 9 | LV2N | mini-LVDS data signal | ⁶⁾ |
| 10 | GND | Ground | |
| 11 | LV3P | mini-LVDS data signal | ⁶⁾ |
| 12 | LV3N | mini-LVDS data signal | ⁶⁾ |
| 13 | GND | Ground | |
| 14 | LV4P | mini-LVDS data signal | ⁶⁾ |
| 15 | LV4N | mini-LVDS data signal | ⁶⁾ |
| 16 | GND | Ground | |
| 17 | LV5P | mini-LVDS data signal | ⁶⁾ |
| 18 | LV5N | mini-LVDS data signal | ⁶⁾ |
| 19 | GND | Ground | |
| 20 | CLKP | mini-LVDS data clock | ⁶⁾ |
| 21 | CLKN | mini-LVDS data clock | ⁶⁾ |
| 22 | GND | Ground | |
| 23 | LV6P | mini-LVDS data signal | ⁶⁾ |
| 24 | LV6N | mini-LVDS data signal | ⁶⁾ |
| 25 | GND | Ground | |
| 26 | LV7P | mini-LVDS data signal | ⁶⁾ |
| 27 | LV7N | mini-LVDS data signal | ⁶⁾ |
| 28 | GND | Ground | |
| 29 | LV8P | mini-LVDS data signal | ⁶⁾ |
| 30 | LV8N | mini-LVDS data signal | ⁶⁾ |
| 31 | GND | Ground | |
| 32 | LV9P | mini-LVDS data signal | ⁶⁾ |
| 33 | LV9N | mini-LVDS data signal | ⁶⁾ |
| 34 | GND | Ground | |
| 35 | LV10P | mini-LVDS data signal | ⁶⁾ |
| 36 | LV10N | mini-LVDS data signal | ⁶⁾ |
| 37 | GND | Ground | |
| 38 | LV11P | mini-LVDS data signal | ⁶⁾ |
| 39 | LV11N | mini-LVDS data signal | ⁶⁾ |
| 40 | GND | Ground | |
| 41 | CKV | Gate clock | |
| 42 | GND | Ground | |
| 43 | SPH1 | Source driver start pulse | ⁵⁾ |
| 44 | SPH2 | Source driver start pulse | ⁵⁾ |
| 45 | SPV1 | Gate driver start pulse | ⁵⁾ |
| 46 | SPV2 | Gate driver start pulse | ⁵⁾ |
| 47 | SHR | Source driver scan direction control | ⁵⁾ |
| 48 | UD | Gate driver scan direction control | ⁵⁾ |
| 49 | OEH | Source driver output enable | ⁴⁾ |
| 50 | LEH | Source driver latch enable | |
| 51 | DSEL | Source driver data input select | ³⁾ |

- 1) STBYB = L: mini-LVDS standby.
- 2) MODE = H: Normal Single Pulse / MODE = L: No Output Pulse
- 3) DSEL = H: 12-pair mini-LVDS (with TTL_SEL = L)
- 4) OEH = H: Source outputs are enabled / OEH = L: Source outputs forced to GND when output polarity change. (Default)
- 5) Set the scan direction as follows.

| Scan Direction | UD | SPV1 | SPV2 | SHR | SPH1 | SPH2 | Remarks |
|----------------------------|----|-------|--------|-----|-------|--------|---------|
| S1 to S2160 G1 to G3060 | H | Input | Output | L | Input | Output | |



- 6) The Common Voltage (VCOM) and Wave Form (WF) for optimal image control for each individual TFT-EPD Open-Cell to be combined must be written into the ROM of this C-PWB by the customer. Each information is shown on the Open-Cell Label 1 as follows.



| Parameters | Contents | References |
|------------|--|------------------------|
| VCOM | Write the value listed on the Open-Cell Label 1. e.g., -0.9 V | ① of Open-Cell Label 1 |
| WF | Select and write a file in which the FPL Lot No. on the Open-Cell Label 1 matches the digits that indicates it in the file name of the WF file (.wbf) provided separately. e.g., E6 _ <u>SPR039</u> _ L10228_EL285TW2F1-R2_ED2208PHB_TC_wbf 1 2 1 3 1: Manufacturer Management Digit <u>2: FPL Lot No.</u> 3: File extension | ② of Open-Cell Label 1 |

4.3. Absolute Maximum Ratings

(GND = 0 V)

| Items | Symbols | Conditions | Ratings | Units | Remarks |
|-------------------------------------|---------------|----------------------------|---------------|--------------------|---------|
| Power Supply Voltage | V_{IN} | $T_a = 25^{\circ}\text{C}$ | -0.3 to +14.5 | V | |
| USB 2.0 Data Voltage | $V_{DATA+/-}$ | $T_a = 25^{\circ}\text{C}$ | -0.3 to +3.3 | V | |
| Storage Temperature ¹⁾ | T_{stg} | - | -25 to +60 | $^{\circ}\text{C}$ | |
| Operation Temperature ¹⁾ | T_{opa} | - | 0 to +50 | $^{\circ}\text{C}$ | |

- Humidity: 95% RH Max. ($T_a \leq 40^{\circ}\text{C}$)
- Maximum wet-bulb temperature at 39°C or less. ($T_a > 40^{\circ}\text{C}$), No condensation.

- 1) After installation, the Open-Cell specifications must be followed.

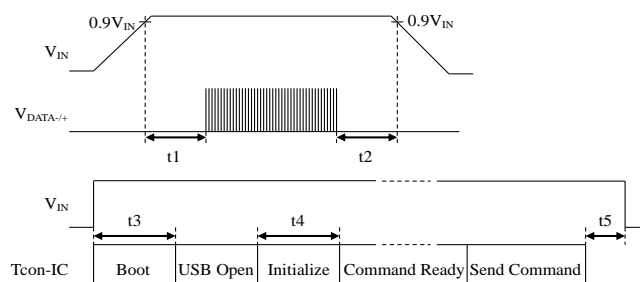
4.4. Electrical Characteristics of Input Signals (w/ TFT-EPD Open-Cell)

(GND = 0 V)



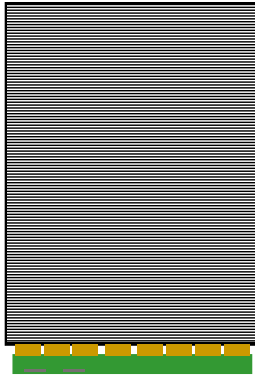
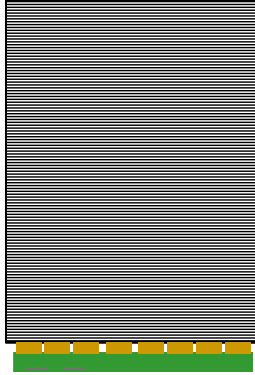
| Items | Symbols | Min. | Typ. | Max. | Units | Remarks |
|---------------------------------------|------------|---------------|------|-------|-------|--|
| Power Supply ¹⁾ | V_{IN} | 11.5 | 12.0 | 12.5 | V | ¹⁾ |
| Current Consumption ^{2), 3)} | I_{IN} | - | 160 | (500) | mA | $V_{IN} = +12.0\text{ V}$ |
| Inrush Current ⁴⁾ | I_{RUSH} | - | 19.6 | - | A | $V_{IN} = +12.0\text{ V}$ ($t = 200\text{ }\mu\text{s}$) |
| USB Data ¹⁾ | Idle | $V_{DATA+/-}$ | -10 | - | 10 | ¹⁾ |
| | High | | 360 | - | 440 | |
| | Low | | -10 | - | 10 | |

- 1) ON/OFF Sequences

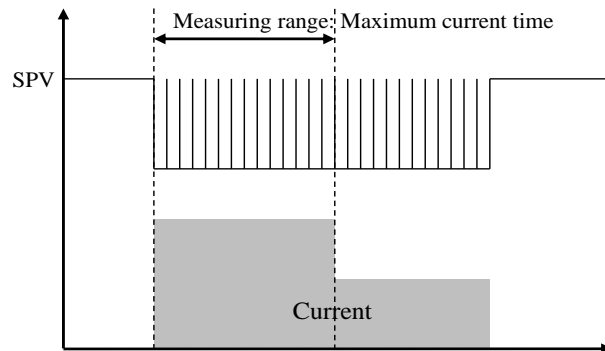
| Items | Min. | Typ. | Max. | Units | Remarks |
|-------|------|------|------|-------|---------|
| t1 | 100 | - | - | ms | |
| t2 | 100 | - | - | ms | |
| t3 | - | 2 | - | s | |
| t4 | - | 2 | - | s | |
| t5 | 500 | - | - | ms | |



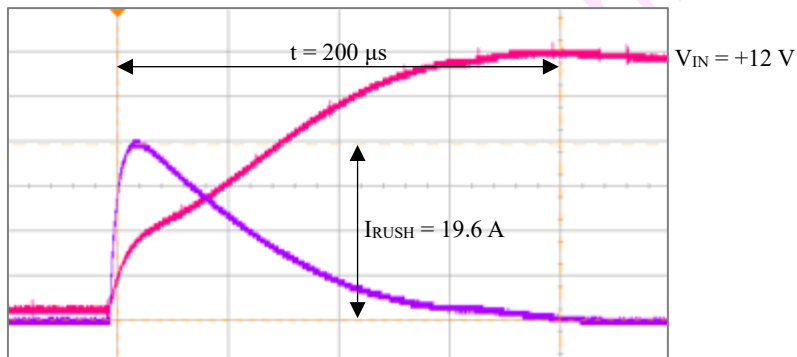
- 2) The typical average current for power consumption is defined in the following screen pattern transitions at 50 Hz waveform.

| Typ. | | Max. | |
|---|---|--|---|
| 6-color Horizontal Stripe | 6-color Vertical Stripe | 2H Line Stripe | 2H Line Stripe (2H line shift) |
|  |  |  |  |

- 3) The measurement range of current consumption defined by the following diagrams.



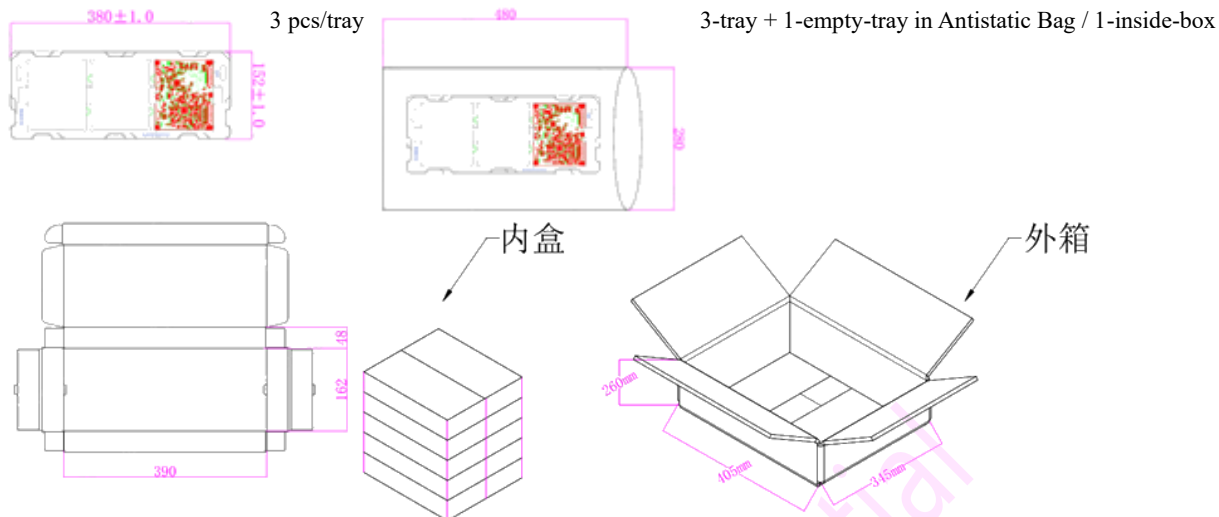
- 4) $V_{IN} +12\text{ V}$ inrush current waveform



5. Delivery Specifications

5.1. Packing Form

| | 1-box | (1-inside-box) |
|--------|-----------------------------------|--|
| Size | 405 x 345 x 260 [mm] | (390 x 162 x 48 [mm]) |
| Q'ty | 90 pcs (= 2-inside-box x 5-layer) | (9 pcs (= 3-pc x 3-tray + 1-empty-tray)) |
| Weight | 7.55 kg | 0.7 kg |



5.2. Identifications

| PWB | Packing |
|---|---|
| <p>The following information are laser marked on the Silk Area.</p> <p>① QR Code [25-digit] e.g., TS RUNTK7033TPZZ 5 2 R 00001 08 1 2 3 4 5 6 1 1: Manufacturer Management Digit 2: SDTC Part Code 3: Production Year (2025) 4: Production Month (1 to 9, A=10, B=11, C=12) 5: Production Date (1 to 9, A=10 to X=31) 6: Serial Number (00001 to 99999)</p> <p>② Characters e.g., 52R0000108 - Z 1 2 1: Same as 16th digit to 23rd digit of QR Code 2: Suffix of SDTC Part Code (RUNTK7033TPZZ)</p> | <p>The following label is attached on each box.</p> <p><u>Manufacture Label</u> e.g.,</p> <p>① SDTC Part Code: RUNTK7033TPZZ ② Packing Quantity: pcs/box ③ Packing Date: YYYY.MM.DD ④ Packing Lot No.1: 000000 to 999999 ⑤ Packing Lot No.2: e.g., L91 # RUNTK7033TPZZ 20250221 00002 ### 090 1 2 3 4 5 1: Manufacturer Management Digit 2: SDTC Part Code (Same as ①) 3: Packing Date (Same as ③) 4: (To be confirmed) 5: Packing Quantity (Same as ②)</p> |

6. Reliability


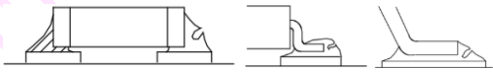
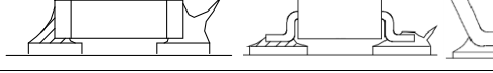
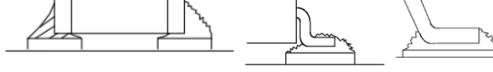
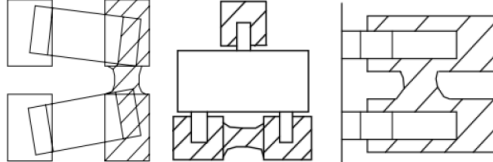
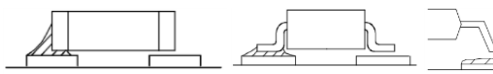
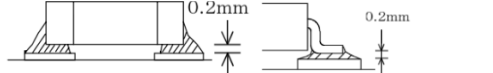

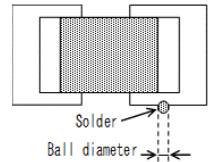
| No. | Test Items | Conditions |
|-----|---|---|
| 1 | High temperature storage test ²⁾ | Ta = 60°C, 35% RH, 240 hours |
| 2 | Low temperature storage test ²⁾ | Ta = -25°C, 240 hours |
| 3 | High temperature and high humidity storage test ²⁾ | Ta = 60°C, 80% RH, 240 hours (No condensation) |
| 4 | High temperature and high humidity operation test ^{1), 2)} | Ta = 40°C, 90% RH, 240 hours (No condensation) |
| 5 | High temperature operation test ^{1), 2)} | Ta = 50°C, 30% RH, 240 hours |
| 6 | Low temperature operation test ^{1), 2)} | Ta = 0°C, 240 hours |
| 7 | Temperature cycle storage test ²⁾ | Ta = -25°C (30 min) \leftrightarrow 60°C (30 min), 50 cycle |
| 8 | ESD test ²⁾ | Input: ± 250 V, 0-ohm, 200 pF (Machine Model, Non-operation) |
| 9 | Packing vibration test ²⁾ | Frequency: 5 to 50 Hz, Round-trip time (3 min/time) Acceleration: Constancy 1G, X/Y axis: 15 min, Z axis: 60 min |
| 10 | Packing drop test ²⁾ | Hight: 75 cm from the concrete or iron board 1 corner, 3 edges, and 6 faces |

1) The operation test is performed with the TFT-EPD Open-Cell [LP285A6NW01] being rewritten every 150 sec.

2) The following items shall be satisfied.

- There shall be no defects in the quality standard in the next section.
- Meet the driving conditions specified in the specifications of TFT-EPD Open-Cell [LP285A6NW01].
- No defects in the display of TFT-EPD Open-Cell [LP285A6NW01].

7. Quality Standard

| No. | Check Items | |
|-----|---|--|
| 1 | No solder cracks. |  |
| 2 | No solder holes. |  |
| 3 | No spike soldering. |  |
| 4 | No cold soldering. Solder surface should show glossing. |  |
| 5 | No solder bridges. |  |
| 6 | No solder loss. |  |
| 7 | Soldering thickness Terminal, lead, or electrode of any part should not be lifted away from the board more than 0.2mm. |  |
| 8 | Incomplete soldering. No exposed terminal surface due to insufficient solder flow. |  |
| 9 | Solder Ball diameter ≤ 0.3 mm 0.05 to 0.3 mm: 8 pcs or less 0.05 mm or less: No Count |  |

| | | |
|----|---|--|
| 10 | <p>Fillet of solder</p> <ul style="list-style-type: none"> - Electrode components $0.3 \text{ mm} < \text{amount of solder} < t+0.5 \text{ mm}$ (Excluding those with no reliability impact.) - Lead components Back fillet height $\geq t$ Fillet formation as “amount of solder $> 1/2t$” (t: Thickness of the lead electrode) | |
| 11 | <p>Part floating: 0.2 mm or less</p> <p>Parts in areas with height restrictions are defined separately. (DC-DC: 0.1 mm or less)</p> | |
| 12 | <p>Misalignment components</p> <ul style="list-style-type: none"> - Electrode components Horizontal: $a > 1/2$ of terminal, $b > 0 \text{ mm}$ Vertical: $c \geq 2/3W$, $d > 0.3 \text{ mm}$ θ Shift: Contact Area $\geq 2/3 \times$ Electrode Area - Lead components Horizontal: $a > 2/3W$, $1/3A$ Vertical: $b > 0 \text{ mm}$ | |
| 13 | <p>$d4 \geq 0.3 \text{ mm}$: NG</p> <p>d4: CNT pin edge to pad outside</p> | |
| 14 | No short circuit between connector terminals and power line. | |
| 15 | No expansion of PWB surface. No delamination between layers. | |
| 16 | No foreign materials, such as flux, solder resist, silk, solder, etc., shall adhere in the plating area and the inside diameter of the hole. | |
| 17 | No Cu exposure in the plating area. | |
| 18 | No pattern defects, dents, or pinholes of 0.2 mm dia. or larger in the plating area. | |
| 19 | <p>Scratch in the plating area.</p> <ul style="list-style-type: none"> - Line width $\leq 200 \mu\text{m}$ - Distance $\geq 1 \text{ mm}$ <p>Scratch on the gold plating layer only (without Ni exposure).</p> <ul style="list-style-type: none"> - Ignore (width, distance) | |
| 20 | No chips, cracks, or burrs on the edge of PWB. | |
| 21 | Various markings, silk, laser marking, etc., on the surface of the PWB must be identifiable with certainty. | |
| 22 | Conducting as per the circuit diagram. | |

8. Precautions

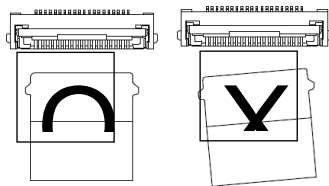
- 1) Handle the C-PWB with the extreme care using the grounded anti-static wrist band to protect electronic circuits with CMOS-ICs from electrostatic breakdown.

- Reference: Process control standard of sharp

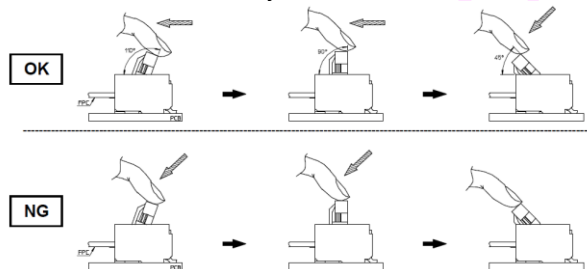
| No. | Items | Management standard value and performance standards |
|-----|--|---|
| 1 | Anti-static mat (floor) | 1 to 50 [Mohm] |
| 2 | Anti-static mat (shelf, desk) | 1 to 100 [Mohm] |
| 3 | Ionizer | Attenuate from ± 1000 V to ± 100 V within 2 sec |
| 4 | Anti-static wrist band | 0.8 to 10 [Mohm] |
| 5 | Anti-static wrist band entry and ground resistance | Less than 1000 ohm |
| 6 | Temperature | 22 to 26 [°C] |
| 7 | Humidity | 60 to 70 [%] |

- 2) Do not touch with chemical-treated clothes or greasy fingers, etc., as some components may degrade the surface.
- 3) Dust on the surface of each component should be blown away with an N2 blower such as an ionizing air gun with anti-static measures.
- 4) Handle the Open-Cell with great care so that it is not dropped or bumped on a hard surface to prevent the glass, the main constituent material, from breaking or cracking.
- 5) Take care to keep the PWB from any stress or pressure when handling or installing the Open-Cell.
- 6) Do not store the PWB in the environment of oxidization or deoxidization gas for a long time and not use such materials as reagent, solvent, adhesive, resin, etc., which generate these gasses when assembling them into cabinets to prevent corrosion and discoloration.
- 7) Applying too much force and stress to the PWB may cause a malfunction electrically and mechanically.
- 8) Handle with care based on the general connector's specification when inserting and removing it.

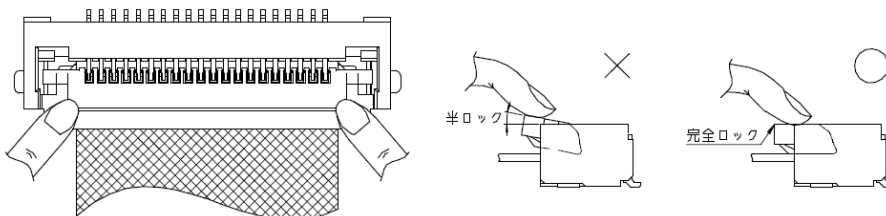
- Do with the actuator opened completely and insert it in the interior of the insertion entrance surely horizontally when you insert FPC. (Put the FFC or FPC tab in the ditch of the housing surely with the FPC tab.) Might it become short defective, and it causes the corner to transform the caught terminal into the terminal by the pitch gap when inserting it right and left and diagonally.



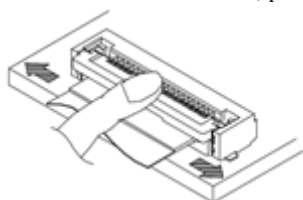
- Add force in the direction where the actuator is held and do by rotating it pushing in parallel to the C-PWB direction when becoming 90° or less as shown in the figure below until the angle of the actuator becomes 90° or less when you shut the actuator. Do not add the force to rotary axis of actuator in the direction that the actuator is off.



- When you lock, it should be push on both sides of the actuator. And it is necessary to confirm that the actuator is surely shut.



- After the actuator is closed, press down the surface of actuator with soft pressure in order to lock as shown in the following figure.



- 9) Turn off the power supply when inserting or disconnecting the cable.
- 10) Consider the design of power protection circuit in case of failure of this PWB according to the customer's operating conditions.
- 11) EMC should be fully verified with the customer's final product.
- 12) The chemical compound, which causes the destruction of ozone layer, is not being used.

- 13) This PWB is corresponded to RoHS.
- 14) The ozone-depleting substances is not used.
- 15) Follow the regulations when the PWB is scrapped.
- 16) When parts specifications or materials and production process will be changed, SDTC will submit to written proposal to the customer and change these after customer's acceptance.
- 17) Refer to the latest Design Notice of the Open-Cell for other precautions as well.
- 18) The OPEN-CELL SPECIFICATIONS should be thoroughly reviewed.
- 19) When any question or issue occurs, it shall be solved by mutual discussion.

9. Storage Conditions

| Items | Before opening the inside box | (Reference: After opening the inside box) |
|------------------|---|---|
| Temperature | 0°C to 40°C | (18°C to 28°C) |
| Humidity | 35% RH to 75% RH | (40% RH to 60% RH) |
| Atmosphere | Harmful gas, such as acid and alkali which bites electronic components and/or wires must not be detected. | |
| Anticondensation | Be sure to put boxes on the airy pallet or base, do not put it on floor, and store them with removing from wall. Take care of ventilation in storehouse and around cartons, and control changing temperature is within limits of natural environment. | |
| Vibration | Refrain from keeping the product in the place which always has vibration. | |
| Storage life | Within 6 months | (Within 7 days) |